12th MiNaPAD conference

Micro/Nano-Electronics Packaging & Assembly, Design and Manufacturing Forum

June 3-4, 2026 – Grenoble, France

Deadline March 20th, 2026

Call for extended abstracts

Extended abstracts can cover all aspects of **microelectronics packaging technologies**, from design to assembly processes and materials. You can find main items and some example of topics covered hereafter.

We look forward to receiving your contribution! Please see the next page for practical details.

Assembly processes and technologies:
advanced dicing, wafer thinning, back side metallization, Taiko ring holder and removal, die attach and wire bonding, flux deposition, cleaning, dispensing, coating, materials & equipment related to assembly manufacturing and business aspects of the industry. Innovative equipment for assembly & packaging.

Materials equipment and processes:
3D materials, conductive & non-conductive adhesives, underfill, mold compound , disruptive solder alloys, thermal interface...

Advanced packaging :
TSVs, 2.5 & 3D integration, heterogeneous integration, wafer level packaging, embedded IC packages, SiP, PoP, MEMS packaging, advanced substrates, hybrid bonding, Fan Out wafer and panel level processes, Chiplets and bridges integration …

Advanced interconnections:
Flip-chip including ultra-fine pitches approaches, interconnections, IMC studies, bumping techniques (solder bumps, Cu pillars,...), disruptive interconnections, optical connections …

Novel technologies and applications:
IA applications, printed electronics and wearable electronics, Flexible/stretchable packaging, additive manufacturing, nanomaterials for interconnections, nano manufacturing …

Packaging of power devices:
SiC, GaN, Si front-end technologies,
Back side metallization, die attach by Ag sintering, thick wire bonding, copper clip attach, overmolding of large modules, leadframe attach on ceramics …

Imaging & photonics:
Assembly & packaging technologies for optical and photonics applications : imaging, displays, silicon photonics, optical sensors, high energy physics and medical imaging, quantum devices …

Thermal/mechanical simulation and characterization:
Components, boards & system level modelling for : interconnections, interposers, substrates, WLP & embedded packages, power modules, optical packaging, RF and MEMS …

Sustainability in Microelectronics packaging:
Environmental-friendly materials : Lead-free and PFAS-free materials, bio-sourced materials, paper-based PCB, reclyded materials …
Processes : lower temperature processing, materials reclaiming & recycling (water, metals etc .) …

Quality and Reliability:
Applied reliability for LED, Displays, IoT, MEMS, memories, medical devices, chip-package and package-PCB interaction. Life models, failure analysis techniques & characterizations, metrology equipment and inspection methods …

Abstract requirement

The format should be a Word or PDF file with two A4 pages including graphs and pictures.
Your submission must include your mailing address, business phone number and email address.
Please note that the content should not include commercial information.
Please send your abstract to :
imaps.france@orange.fr

Important dates

Abstracts deadline submission date :
March 20th , 2026

Notification of acceptance :
Authors will be notified of paper acceptance with instructions for presentation **before April 8th, 2026.**

Presentations delivery :
Presentation should be ready **one day** before the workshop and supply to the chairwomen or chairmen of your session.

Minatec Congress center, Grenoble

Event information

Organization :

IMAPS France
Email: imaps.france@orange.fr
Web: www.france.imapseurope.org

General chair: Valérie VOLANT (STMicroelectronics)
Technical Chairs:
Jean-Luc DIOT (Assemblinnov),
Romain COFFY (STMicroelectronics),
Jean-Charles SOURIAU (CEA-LETI),
Jean-François SAUTY (ASE),
Laurent MENDIZABAL (CEA-LETI),
Alexandre VAL (VALEO).

Location :

Close to Grenoble Railway Station :
MINATEC Congress Center
3 Parvis Louis Néel
38054 Grenoble Cedex 1
FRANCE

Exhibition area :

Equipment & Product suppliers in the Atrium during the workshop.

Social event :

Evening dinner & visit on the 3th of June 2026

Discount for speaker registration fees

50 % OFF

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